MN1380 Series

CMOS LSIs for Voltage Detection

■ Overview

The MN1380 series are elements that monitor the power supply voltage supplied to microcomputers and other LSI systems and issue reset signals for initializing the system after the power is first applied or for preventing runaway operation when the supply voltage fluctuates.

There is a choice of three output types: CMOS output, N-channel open drain output, and inverted CMOS output. There are also three package types: M, TO-92, and a mini type for surface mounting.

Choose the ideal element for your application from the series' wide selection of detection ranks (17 ranks between 2.0 and 4.9 volts), output types, and package types.

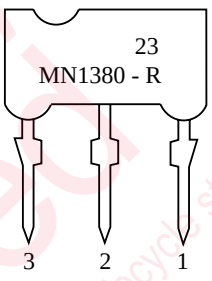
■ Features

- Three-pin element requiring no adjustment
- Wide selection of detection ranks (17 ranks between 2.0 and 4.9 volts)
- Highly precise detection voltage
- Detection voltage with hysteresis characteristic
  ΔVD = 50 mV for ranks C to K
  ΔVD = 100 mV for ranks L to U
- Low current consumption: I_{DD} = 1µA (typ.) for V_{DD} = 5 V
- Low fluctuation in detection voltage with temperature (typ. 1 mV/˚C)
- Wide selection of output types: CMOS output, N-channel open drain output, and inverted CMOS output
- Wide selection of package types: M, TO-92, and a mini type for surface mounting.

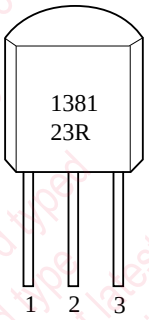
■ Applications

- Battery checkers
- Power outage detectors
- Level discriminators
- Memory backup systems
- Microcomputer reset circuits
- Reset circuits for other electronic circuits

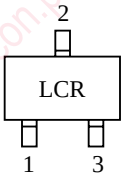
■ Pin Assignment



M type package



TO-92 type package

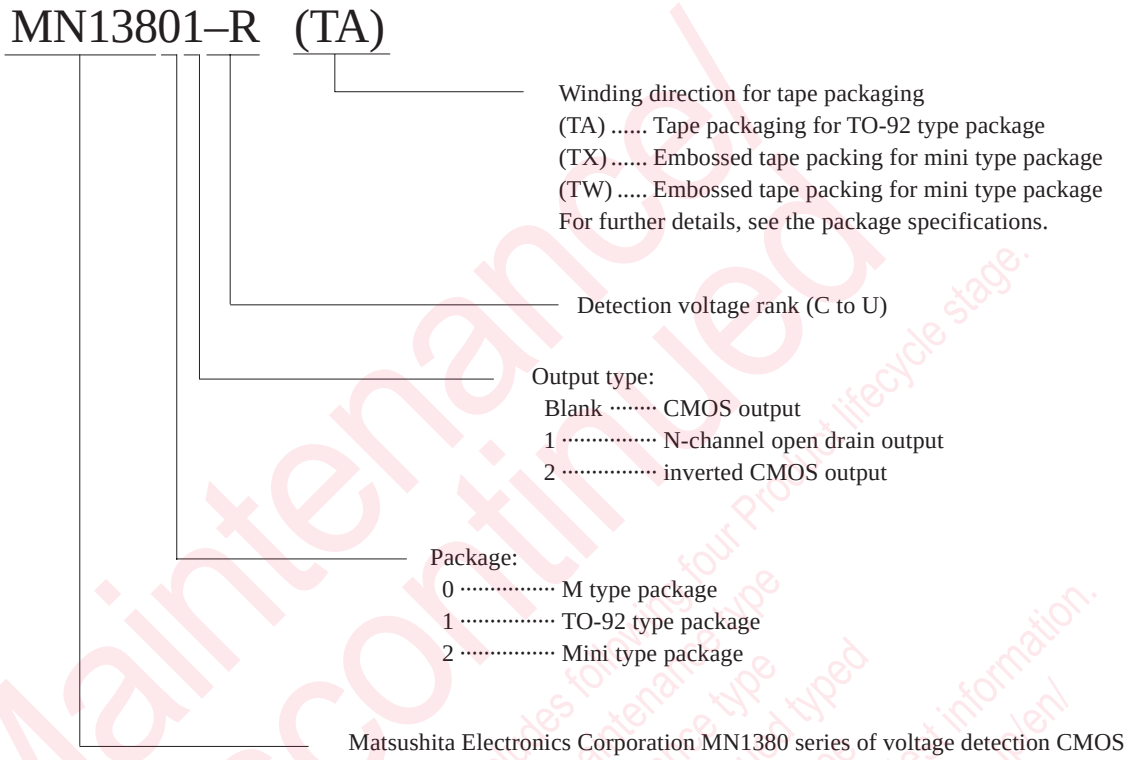


1=OUT
2=V_{DD}
3=V_{SS}

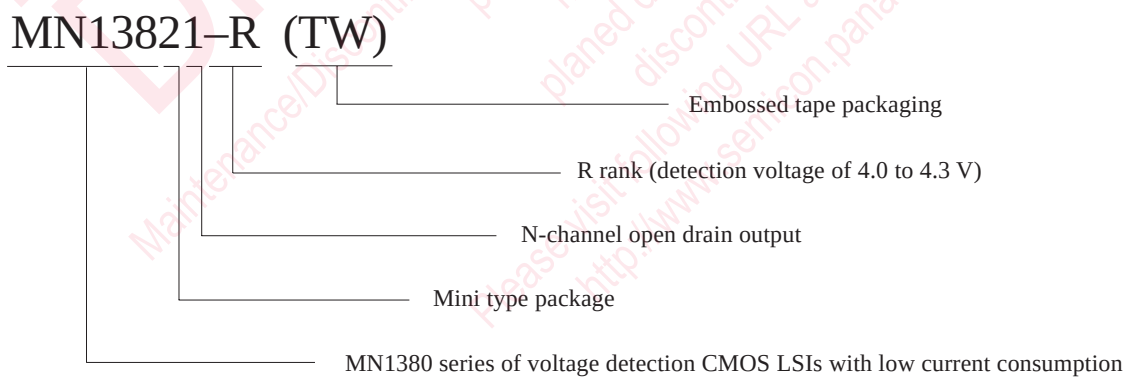
Mini type package

■ MN1380 Series Naming Conventions

The MN1380 series offers a wide selection of detection ranks, output types, package types, and packaging. All combinations use the following naming conventions. When ordering, be sure to give the correct part number using these naming conventions.



(Example)



■ Minimum Packaging Unit

Bulk (M and TO-92 types) ····· 1,000
Magazine (Mini type) ····· 50
Taping (Mini and TO-92 types) ····· 3,000

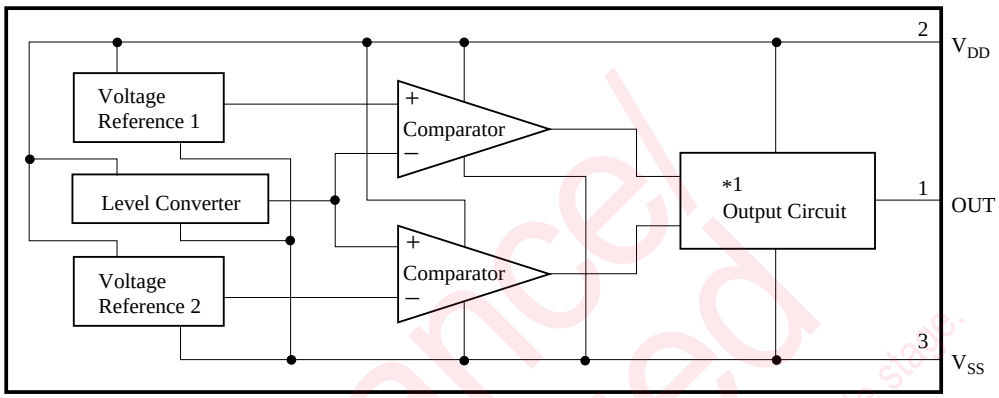
■ Series Lineup

Output \ Package	M type Package	TO-92 type Package	Mini type Package
CMOS output	MN1380	MN1381	MN1382
N-channel open drain output	MN13801	MN13811	MN13821
Inverted CMOS output	MN13802	MN13812	MN13822

■ Detection Ranks (on Voltage)

Rank	Detection Voltage for Drop in Power Supply Voltage (V_{DL})		Unit	Detection Voltage Hysteresis Width (ΔVD)		Unit
	min	max		min	max	
C	2.0	2.2	V	50	300	mV
D	2.1	2.3				
E	2.2	2.4				
F	2.3	2.5				
G	2.4	2.6				
H	2.5	2.7				
J	2.6	2.9	V	50	300	mV
K	2.8	3.1				
L	3.0	3.3	V	100	300	mV
M	3.2	3.5				
N	3.4	3.7				
P	3.6	3.9				
Q	3.8	4.1				
R	4.0	4.3				
S	4.2	4.5				
T	4.4	4.7				
U	4.6	4.9				

■ Block Diagram



Note *1: Circuits vary slightly depending on the output type (CMOS output, N-channel open drain output, or inverted CMOS output)

■ Pin Descriptions

Pin No.	Symbol	Function Description
1	OUT	Reset signal output pin
2	V_{DD}	Power supply pin
3	V_{SS}	Ground pin

■ Absolute Maximum Ratings V_{SS}=0V, Ta=25˚C

Parameter	Symbol	Rating	Unit
Power supply voltage	V_{DD}	7.0	V
Output voltage	V_O	– 0.3 to V_{DD} +0.3	V
Operating ambient temperature	Ta	–20 to +70	˚C
Storage temperature	T_{stg}	–55 to +125	˚C

■ Recommended Operating Conditions V_{SS}=0V, Ta=25˚C

Parameter	Symbol	Conditions	min	typ	max	Unit
Power supply voltage	V_{DD}	See Figures 1 and 4.	1.5		6.0	V

■ Electrical Characteristics

1) DC Characteristics V_{SS}=0V, Ta=–20˚C to +70˚C

Parameter	Symbol	Conditions		min	typ	max	Unit
Power supply current	I_{DD}	V_{DD} = 5 V *1 Load resistance = 10 kW			1	5	µA
Detection voltage for drop in power supply voltage *2	V_{DL}	Ta=25˚C See Figures 1 and 4.		*2		*2	V
Detection voltage hysteresis width *2	ΔVD			*2		*2	mV
"H" level output voltage	V_{OH}	CMOS output	I_{OH}=– 40µA	0.8V_{DD}		V_{DD}	V
		Inverted CMOS output	V_{DD}=1.8V I_{OH}=– 0.5mA	0.8		V_{DD} –1.5	
"L" level output voltage	V_{OL}	N-channel open drain output	V_{DD}=1.8V I_{OL}=0.7mA	V_{SS}		0.4	V
		Inverted CMOS output	V_{DD}=6.0V I_{OH}=0.3mA	V_{SS}		0.6	

Notes

*1: This includes the output pin's leakage current.

*2: For particulars, see the detection voltage rank table.

■ Electrical Characteristics (continued)

2) AC Characteristics V_{SS}=0V, Ta=25˚C

Parameter	Symbol	Conditions	Rank	Allowable Value (typ) MN1380 MN1381 MN1382	Allowable Value (typ) MN13801 MN13811 MN13821	Allowable Value (typ) MN13802 MN13812 MN13822	Unit
Reset release time	t_{OH}	See Figures 2 and 3.	C D E F	3.0	2.5	230.0	µs
			G H J K	3.0	3.0	100.0	
			L M N P Q R S T	2.0	4.0	30.0	
Reset time	t_{OL}	See Figures 2 and 3.	C D E F	250.0	160.0	3.0	µs
			G H J K	115.0	100.0	3.0	
			L M N P Q R S T	15.0	35.0	3.0	

■ Description of Operation

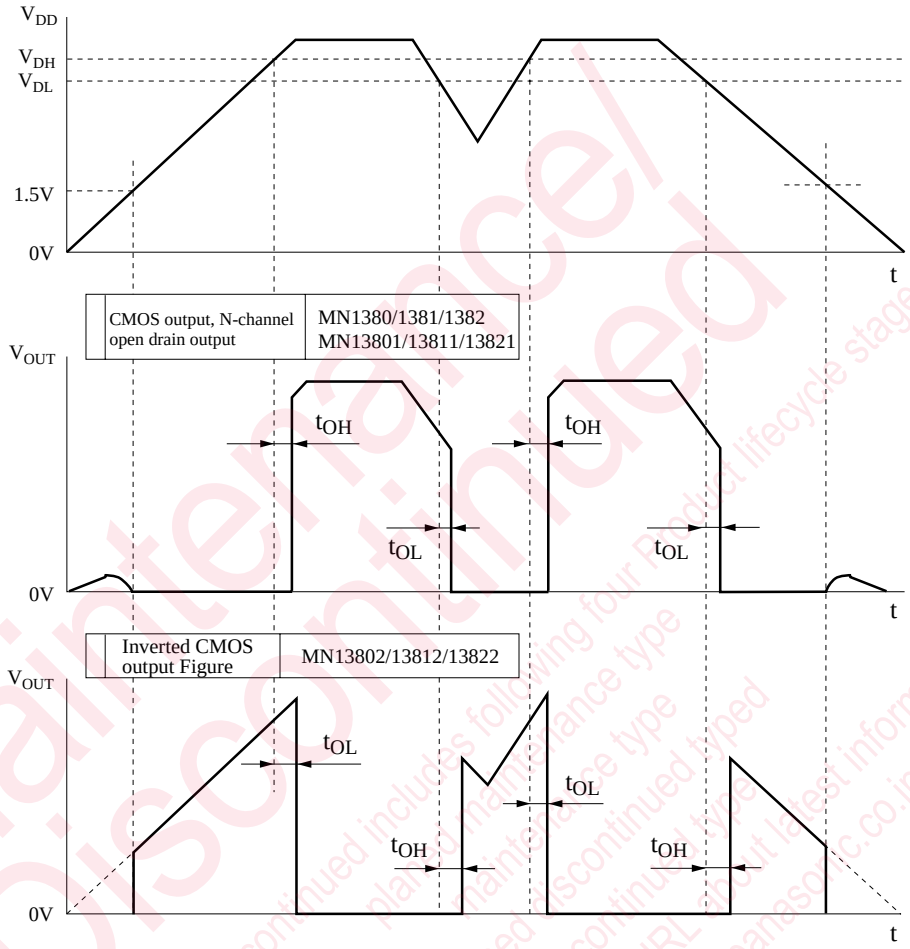


Figure 1. Description of Operation

Notes

1: Output cannot be specified for power supply voltages under 1.5 V because operation is not guaranteed for that range.

2: V_{DL}: Detection voltage for drop in power supply voltage

V_{DH}: Detection voltage for rise in power supply voltage

t_{OL} : Time lag between the time that the power supply voltage reaches the detection voltage (V_{DL} or V_{DH}) and the time that the output pin (OUT) goes to "L" level.

t_{OH} : Time lag between the time that the power supply voltage reaches the detection voltage (V_{DL} or V_{DH}) and the time that the output pin (OUT) goes to "H" level.

3: These characteristics for the N-channel open drain output are when a load resistor is connected between the OUT and V_{DD} pins.

■ Description for Measuring the Output Characteristics

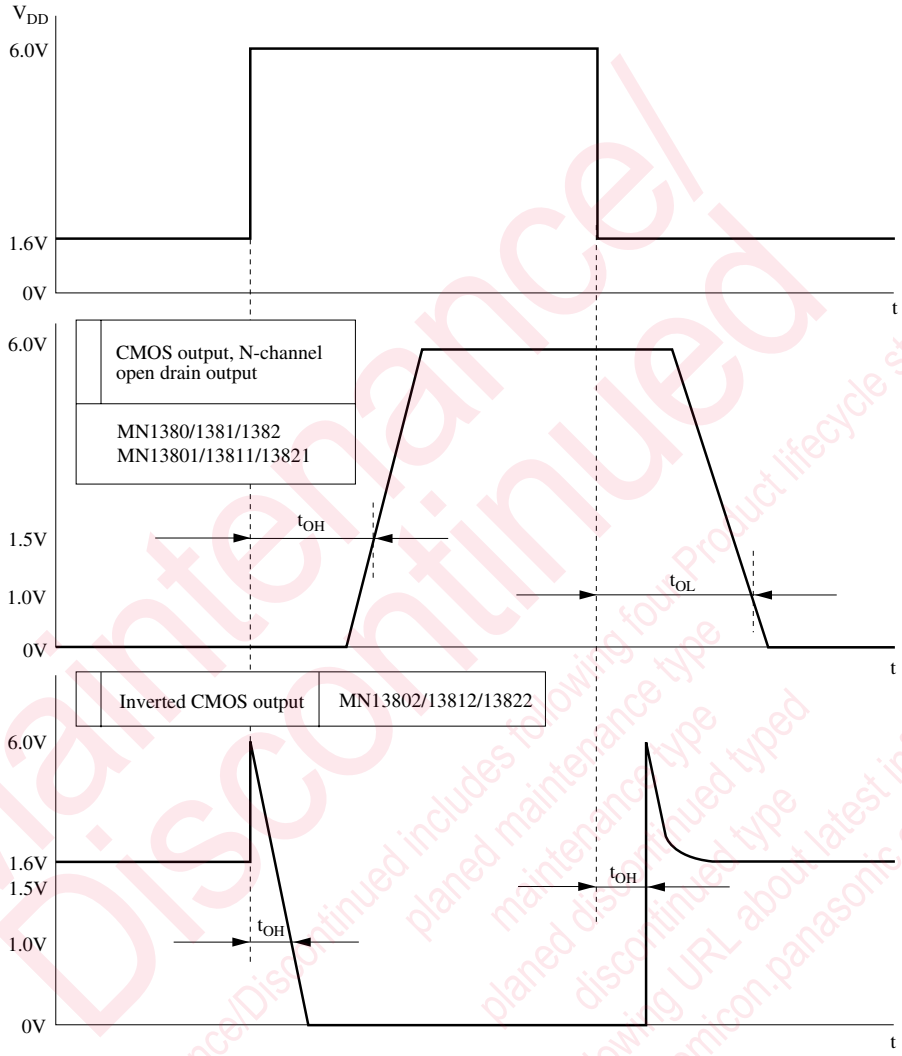


Figure 2. Description chart of Measuring the Output Characteristics

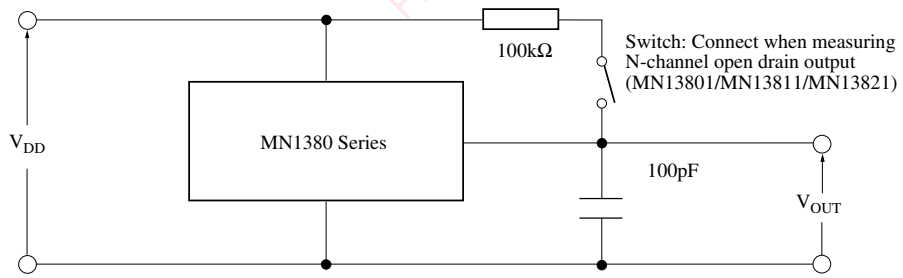


Figure 3. Circuit for Measuring the Output Characteristics

■ Description for Measuring the I/O Characteristics

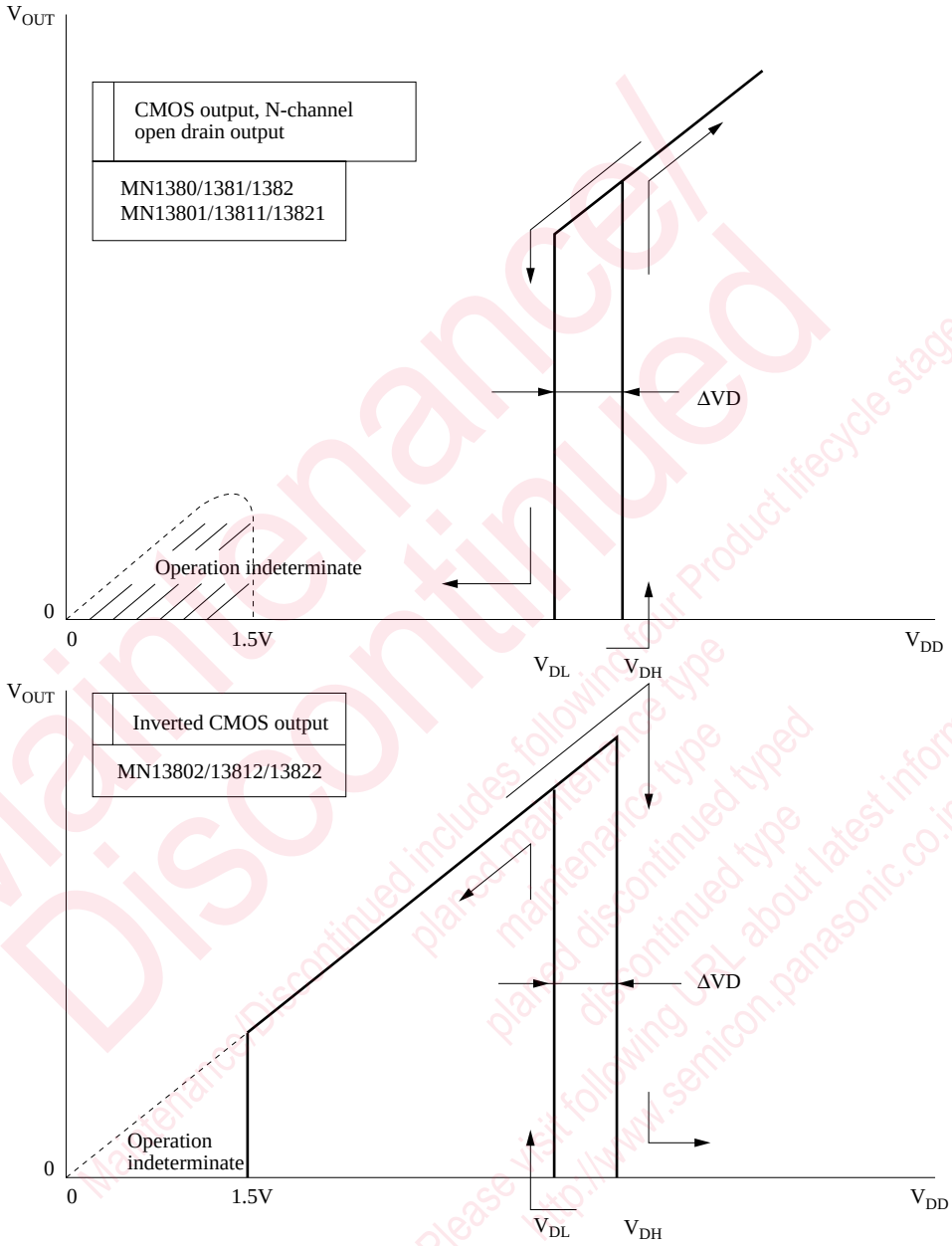


Figure 4. Description chart for Measuring the I/O Characteristics

Notes

1: Output cannot be specified for power supply voltages under 1.5 V because operation is not guaranteed for that range.

2: V_{DL}: Detection voltage for drop in power supply voltage

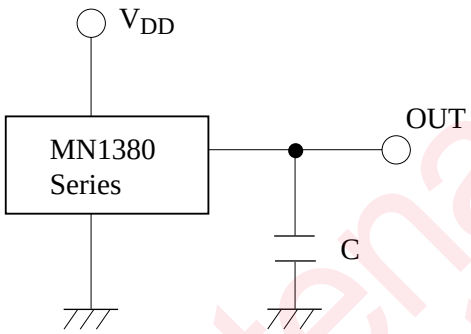
V_{DH}: Detection voltage for rise in power supply voltage

3: These characteristics for the N-channel open drain output are when a load resistor is connected between the OUT and V_{DD} pins.

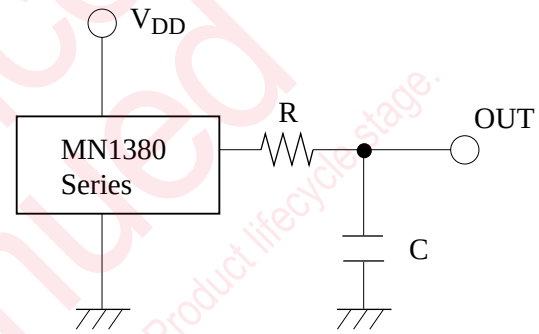
■ Application Circuit Example

Connect resistors, capacitors, and the like only to the output pin on the MN1380 series element. Note that connecting them to the Power source pins changes V_{DH}, V_{DL}, and ΔVD.

Sample Circuit 1



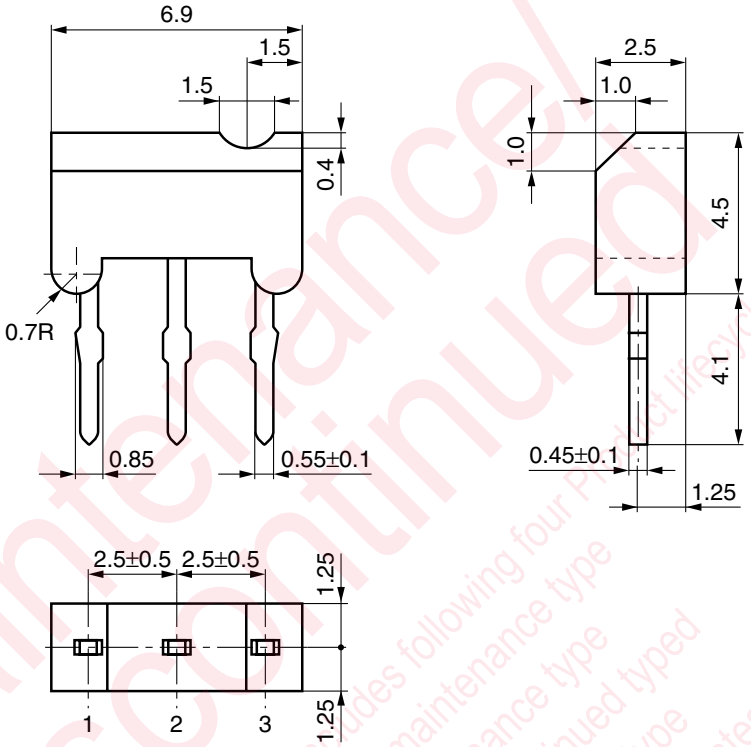
Sample Circuit 2



Select the values of R and C to match the application.

■ Package Dimensions (Unit: mm)

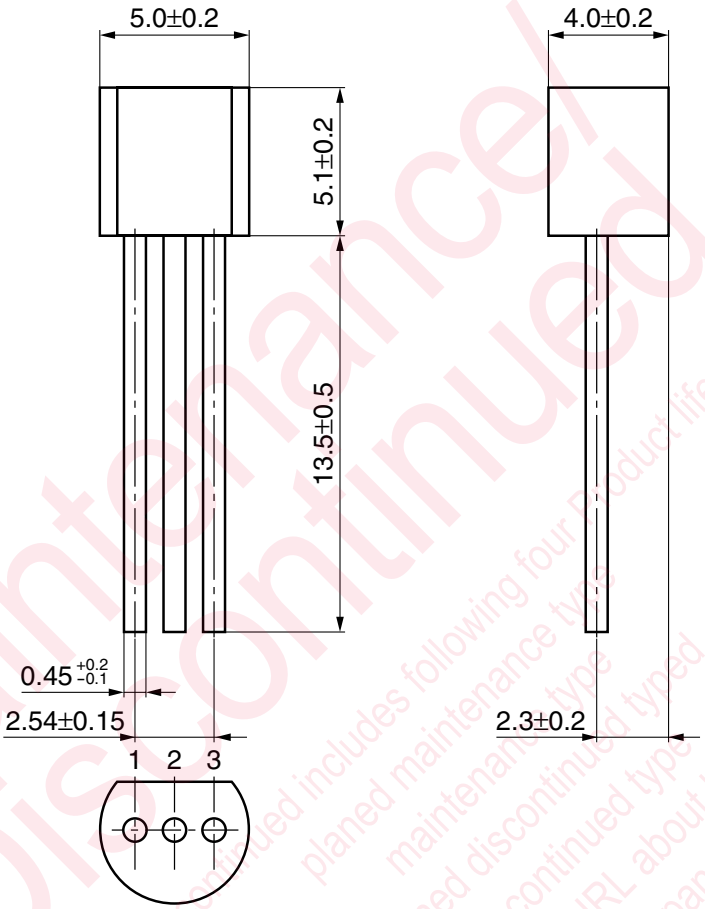
M type package



Note) The package will be changed to lead-free type (M3A). See the new package dimensions section later of this datasheet.

■ Package Dimensions (Unit: mm)(continued)

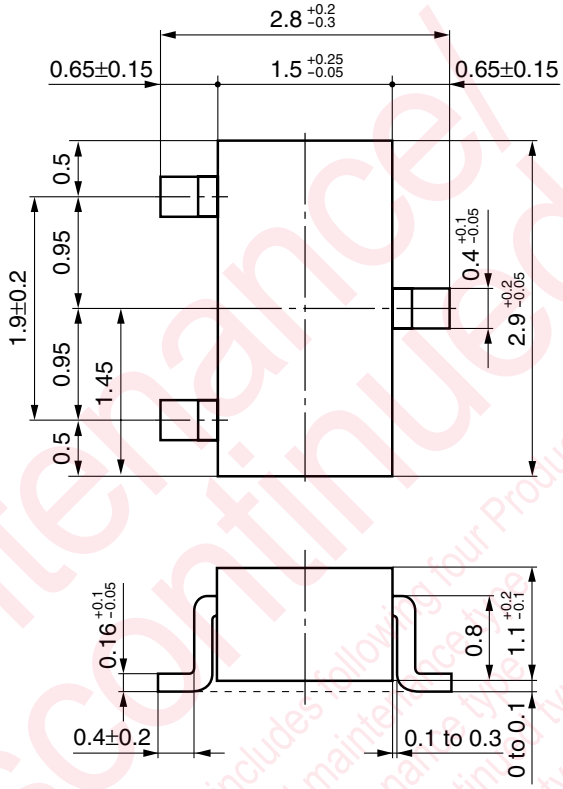
TO-92 type package



Note) The package will be changed to lead-free type (SSIP003-P-0000S). See the new package dimensions section later of this datasheet.

■ Package Dimensions (Unit: mm)(continued)

Mini type package



Note) The package will be changed to lead-free type (MINI-3DC). See the new package dimensions section later of this datasheet.

■ Reference Characteristics

The following characteristics curves represent results from a specific sample therefore they do not guarantee the characteristics for the final product.

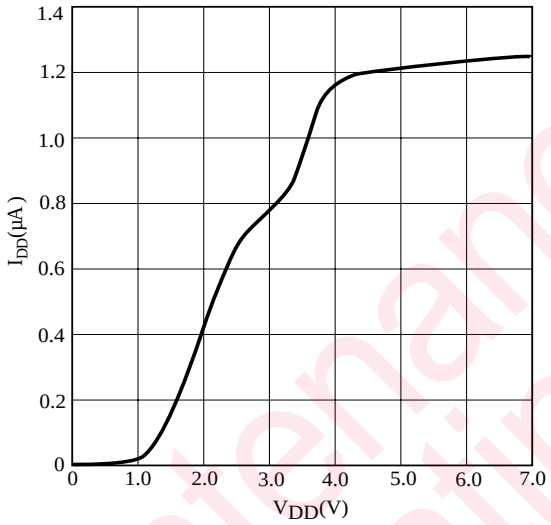


Figure 5.a. I_{DD} vs. V_{DD} Characteristic (Rank Q)

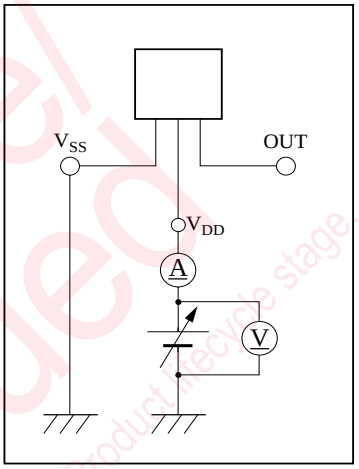


Figure 5.b. Measurement Circuit

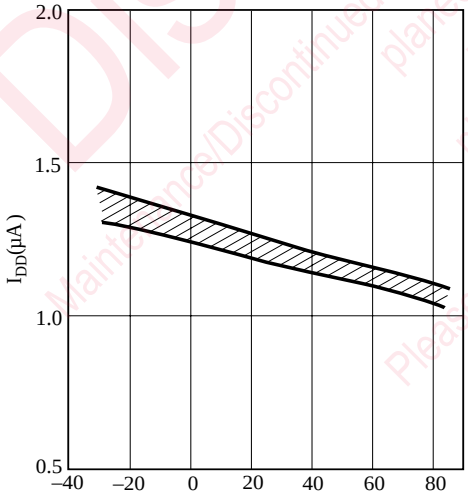


Figure 6.a. I_{DD} Temperature Characteristic (Rank Q)

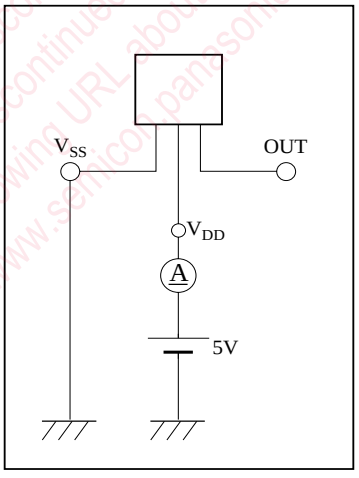


Figure 6.b. Measurement Circuit

■ Reference Characteristics (continued)

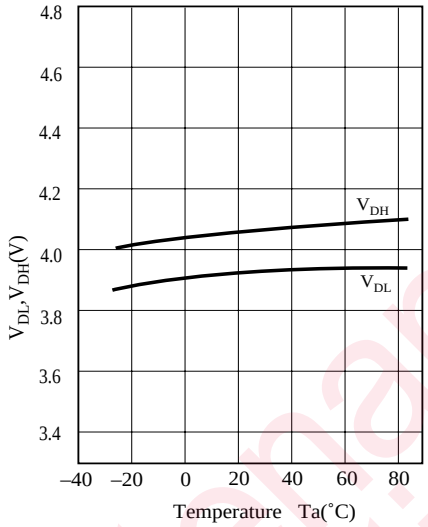


Figure 7.a. V_{DL}/V_{DH} Temperature Characteristic (Rank Q)

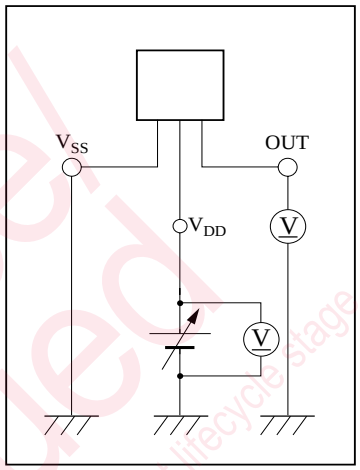


Figure 7.b. Measurement Circuit

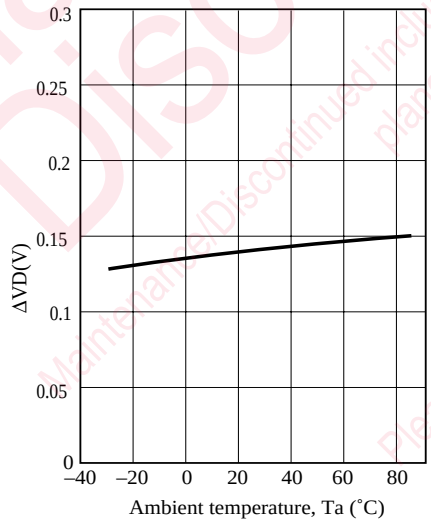


Figure 8.a. ΔVD Temperature Characteristic (Rank Q)

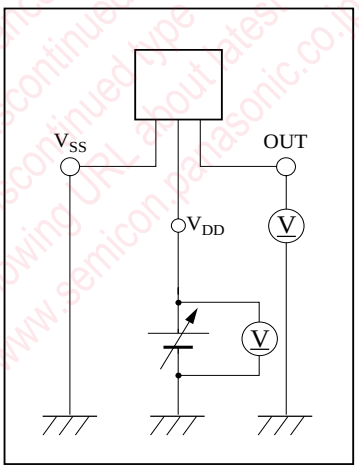


Figure 8.b. Measurement Circuit

■ Reference Characteristics (continued)

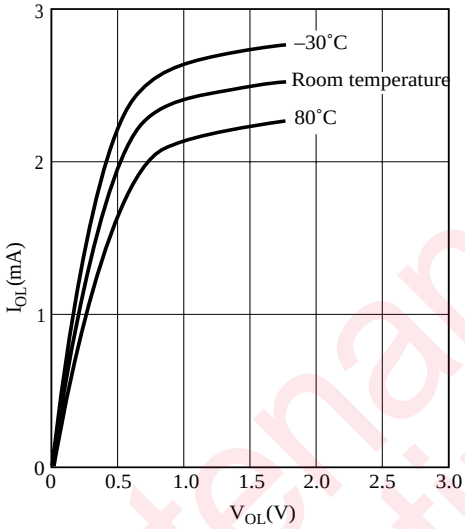


Figure 9.a. I_{OL} vs. V_{OL} Characteristic

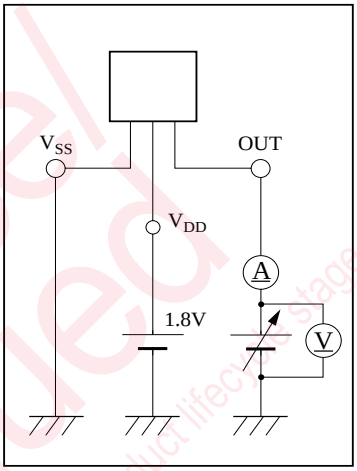


Figure 9.b. Measurement Circuit

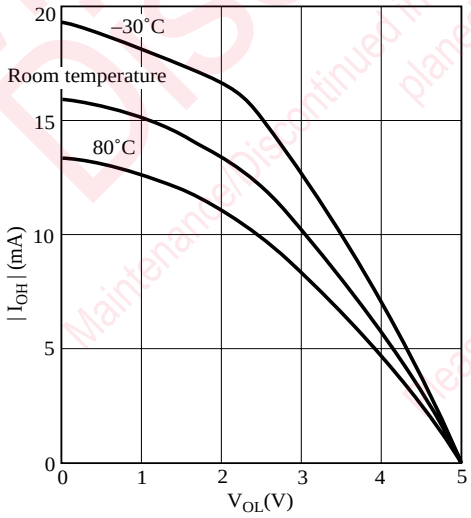


Figure 10.a. I_{OH} vs. V_{OH} Characteristic

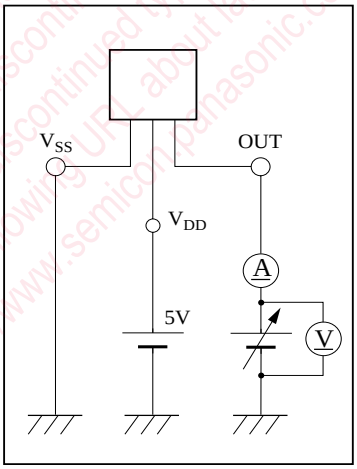


Figure 10.b. Measurement Circuit

■ Reference Characteristics (continued)

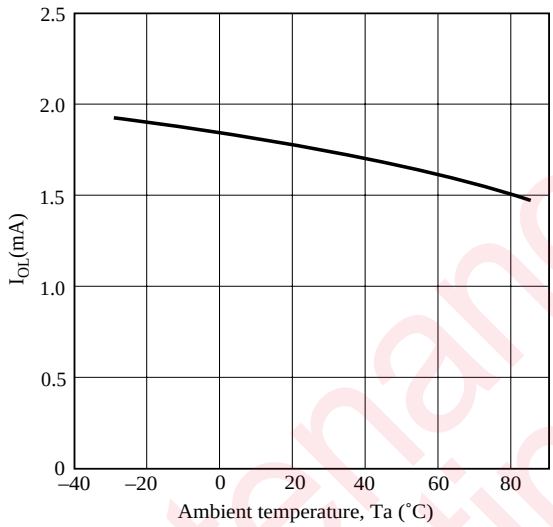


Figure 11.a. I_{OL} vs. Temperature Characteristic

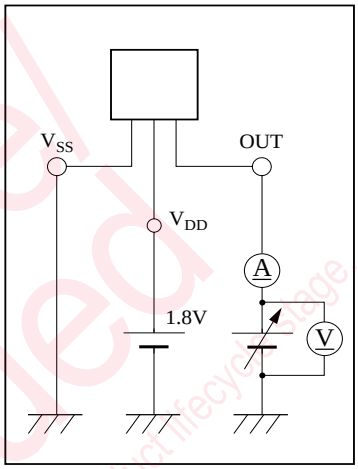


Figure 11.b. Measurement Circuit

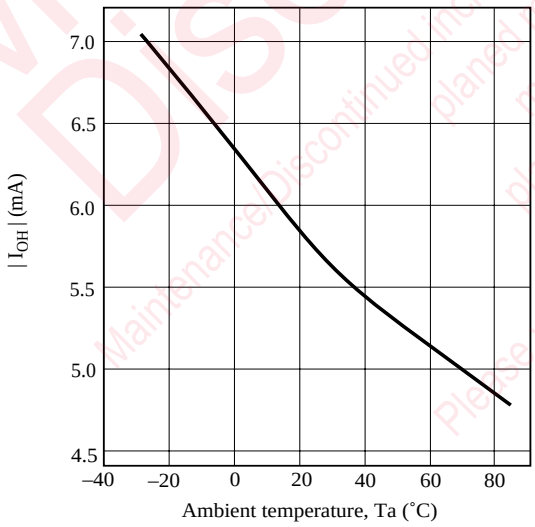


Figure 12.a. I_{OH} vs. Temperature Characteristic

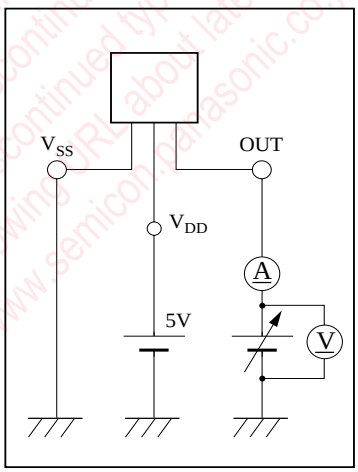


Figure 12.b. Measurement Circuit

■ TO-92 Type Package Taping-Specifications (MN1381/MN13811/MN13812)

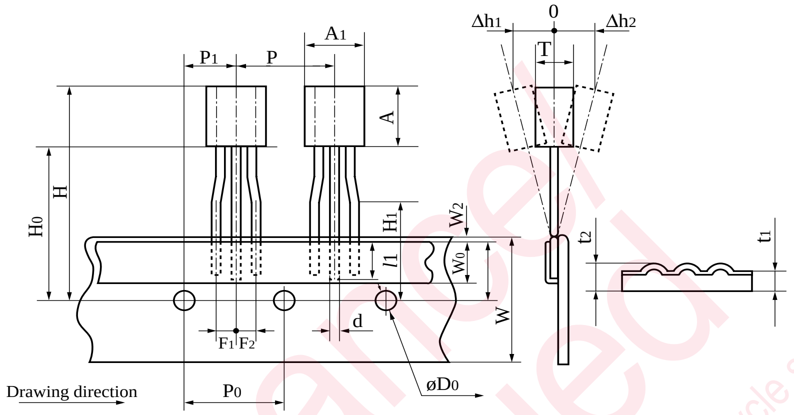


Figure 13. TO-92 Type Package Taping-Dimensions (Ammunition pack)

TO-92 Type Package Taping Dimensions (Ammunition pack)

Name	Symbol	Length (mm)
Product height*	A	5.3 max
Product width*	A1	5.2 max
Product thickness*	T	4.2 max
Lead width*	d	$0.45^{+0.15}_{-0.1}$
Taped lead length	*l*1	2.0 max
Product pitch	P	12.7±1.0
Feed hole pitch	P0	12.7±0.3
Feed hole position	P1	6.35±0.5
Lead spacing	F1, F2	$2.5^{+0.5}_{-0.2}$
Product deflection angle	Δh1, Δh2	2.0 max
Tape width	W	$18.0^{+1.0}_{-0.5}$

Name	Symbol	Length (mm)
Adhesive tape width	W0	6.0±0.5
Feed hole position	W1	9.0±0.5
Adhesive tape position	W2	0.5 max
Distance to top of product	H	25.0 max
Distance to bottom of product	H0	19.0±0.5
Lead clinch height	H1	16.0±0.5
Feed hole diameter	D0	4.0±0.2
Tape thickness	t1	0.7±0.2
Total tape thickness	t2	1.5 max

Note*1: For further details, see the specifications issued separately.

W	H	D
330	250	41

Unit: mm

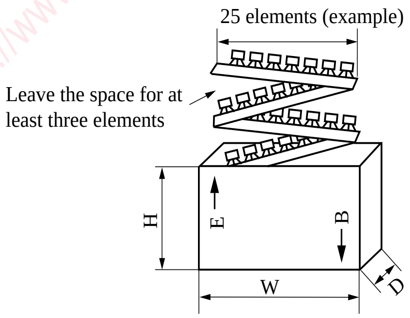
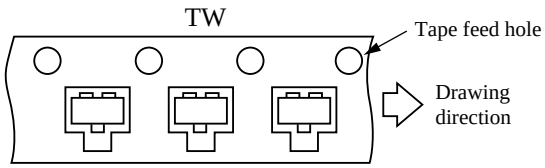


Figure 14. Box Dimensions for TO-92 Type Packages with Ammunition pack

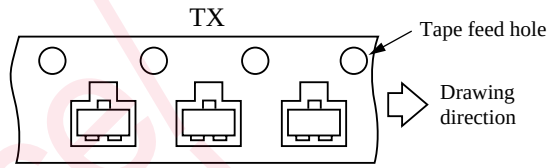
■ Embossed Taping Specifications for Mini Type Package (MN1382/MN13821/MN13822)

There is a choice of two orientations, TW and TX, for the product relative to the tape.



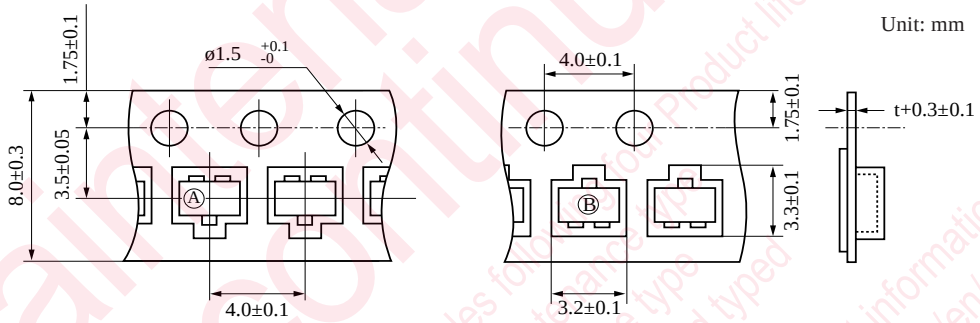
(Marking surface on top)

Figure 15. TW Orientation



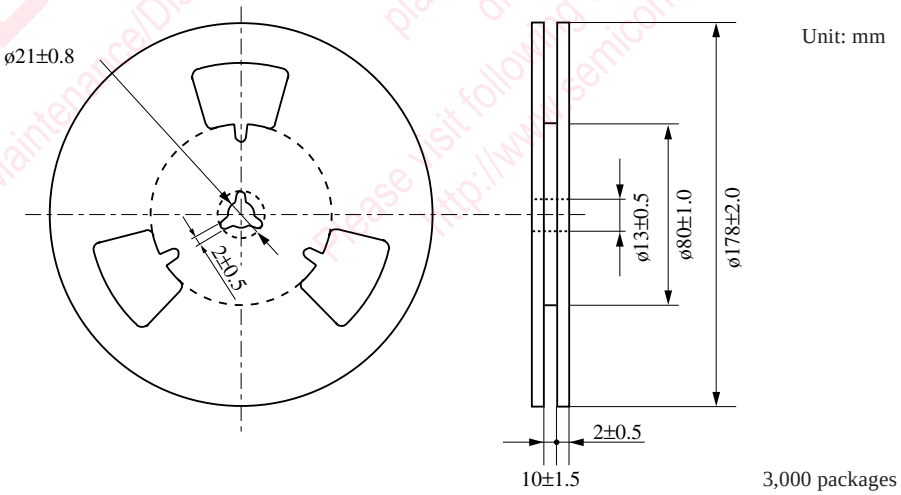
(Marking surface on top)

Figure 16. TX Orientation



Product orientation A is labeled TW; orientation B, TX.

Figure 17. Embossed Taping Dimensions for Mini Type Package



3,000 packages per reel

Figure 18. Embossed Taping Reel Dimensions for Mini Type Package

■ Reliability Testing Results for MN1380 Series

(1) M type package (MN1380/MN13801/MN13802) and TO-92 type package (MN1381/MN13811/MN13812)

Test Subjects	Test Conditions	Results
Operating lifetime test	V_{DD}=5.5V, Ta=125˚C, t=1000hrs	0/15
High-temperature storage test	Ta=150˚C, t=1000hrs	0/15
Low-temperature storage test	Ta=–65˚C, t=1000hrs	0/15
High-temperature, high-humidity storage test	Ta=85˚C, RH=85%, t=1000hrs	0/15
High-temperature, high-humidity bias test	V_{DD}=5.5V, Ta=85˚C, RH=85%, t=1000hrs	0/15
Thermal shock test	Ta=150˚C and –65˚C. Five minutes at each temperature for ten cycles	0/15
Temperature cycle test	Ta=150˚C and –65˚C. Thirty minutes at each temperature for ten cycles	0/15
Pressure cooker test	Two atmospheres for 50 hours at ambient temperature (Ta) of 121˚C	0/15
Soldering test	Ambient temperature (Ta) of 230˚C for five seconds	0/15
Solder heat resistance test	Ambient temperature (Ta) of 270˚C for ten seconds	0/15

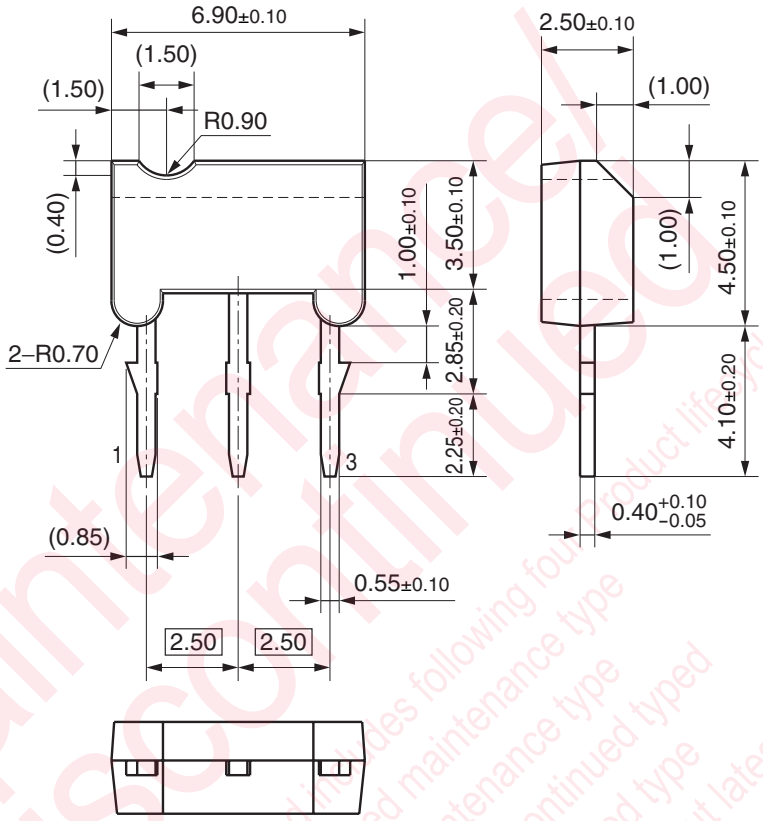
(2) Mini type package (MN1382/MN13821/MN13822)

Test Subjects	Test Conditions	Results
Operating lifetime test	V_{DD}=5.5V, Ta=125˚C, t=1000hrs	0/15
High-temperature storage test	Ta=150˚C, t=1000hrs	0/15
Low-temperature storage test	Ta=–65˚C, t=1000hrs	0/15
High-temperature, high-humidity storage test	Ta=85˚C, RH=85%, t=1000hrs	0/15
High-temperature, high-humidity bias test	V_{DD}=5.5V, Ta=85˚C, RH=85%, t=1000hrs	0/15
Thermal shock test	Ta=150˚C and –65˚C. Five minutes at each temperature for ten cycles	0/15
Temperature cycle test	Ta=150˚C and –65˚C. Thirty minutes at each temperature for ten cycles	0/15
Pressure cooker test *1	Two atmospheres for 24 hours at ambient temperature (Ta) of 121˚C	0/15
Soldering test	Ambient temperature (Ta) of 230˚C for five seconds	0/15
Solder heat resistance test *1	Ambient temperature (Ta) of 260˚C for five seconds	0/15

Note*1: Note that the testing conditions for the mini package differ from those for the other two packages.

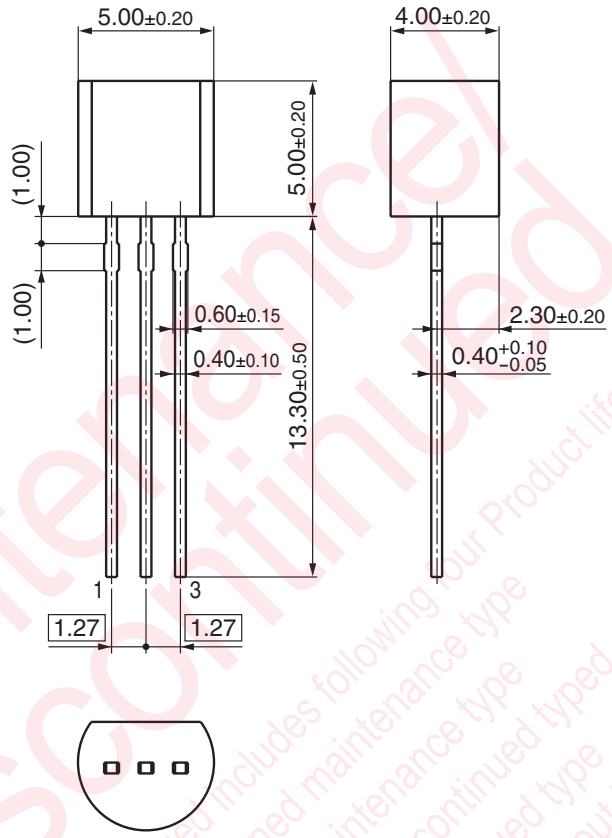
■ New Package Dimensions (Unit: mm)

• M3A (Lead-free package)



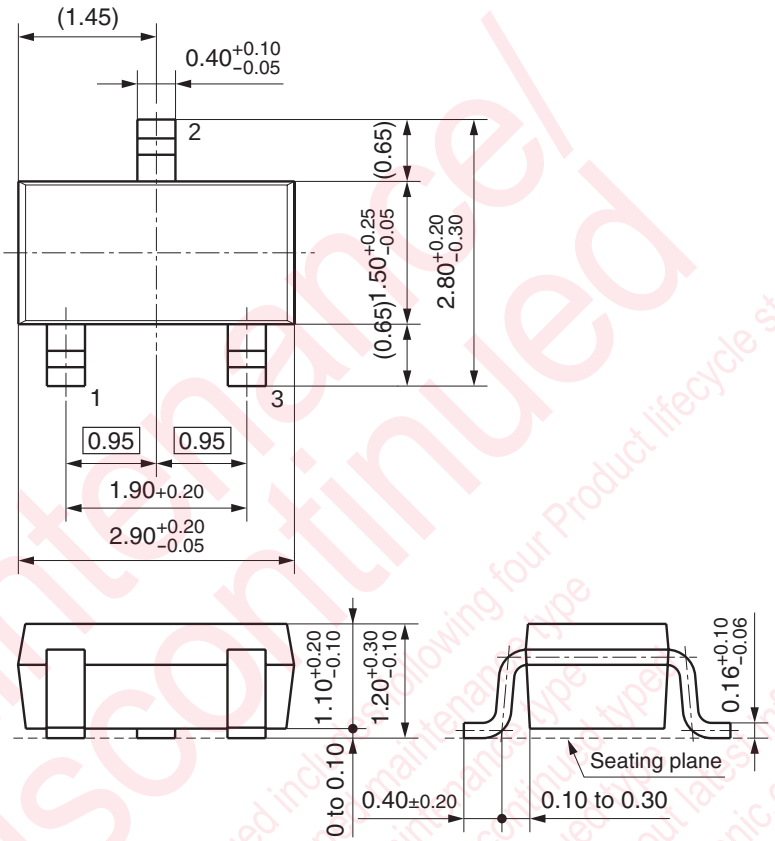
■ New Package Dimensions (Unit: mm)(continued)

- SSIP003-P-0000S (Lead-free package)



■ New Package Dimensions (Unit: mm)(continued)

- MINI-3DC (Lead-free package)



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